

ABSTRACT OF THE DISCLOSURE

5 A substrate with a plurality of semiconductor chips mounted thereon
is set in a die. The die is then clamped. The die thus clamped forms a
space, into which resin is introduced. In doing so, a member is provided to
fill a gap between an upper surface of each chip and the die. The member is
elastic and thus elastically deforms when the die is clamped. Thus from
the elastic member to each chip's upper surface a substantially uniform
pressure is exerted. The elastic member is a film extending substantially
parallel to each chip's upper surface and contacts the upper surface as the
10 member is tensioned in its in-plane direction. The above resin introduction
step can prevent the semiconductor chip from having an upper surface with
resin flash.